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AMENDED CLAIMS

[received by the International Bureau on 22 July 2005 (22.07.05)
original claims 7, 8 & 9 cancelled, original claims 1 to 6 remaining unchanged (1 page)]

1. A dicing/die bonding sheet adhesively bonded to a semiconductor wafer prior to the dicing of said semiconductor wafer, wherein said dicing/die bonding sheet is provided with a base film, an undercoat layer formed on the above-mentioned base film, and a silicone
5 based adhesive agent layer formed on the above-mentioned undercoat layer and having an adhesive surface adhesively bonded to the above-mentioned semiconductor wafer.
2. The dicing/die bonding sheet according to claim 1, wherein the above-mentioned silicone based adhesive agent layer can be stripped from the above-mentioned undercoat layer after bonding to the above-mentioned semiconductor wafer.
- 10 3. The dicing/die bonding sheet according to claims 1 or 2, wherein the above-mentioned undercoat layer is a laminate made up of at least two layers.
4. The dicing/die bonding sheet according to any of claims 1 through 3, wherein the above-mentioned base film has a surface area that is not less than the above-mentioned semiconductor wafer.
- 15 5. The dicing/die bonding sheet according to any of claims 1 through 4, which is coated with a strippable protective layer.
6. A method of preparing the dicing/die bonding sheet according to claim 1, which includes the step of forming an undercoat layer and a silicone based adhesive agent layer on a base film.
- 20 7. (cancelled)
8. (cancelled)
9. (cancelled)

AMENDED SHEET (ARTICLE 19)